

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for curing or drying of a surface-coating layer or of a printing ink, comprising adding to the surface-coating layer or the printing ink one or more ~~Use of pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials materials for curing and/or drying and/or for increasing the thermal conductivity of surface-coating layers and printing inks.~~
2. (Currently Amended) A method ~~Use of semiconductor materials according to Claim 1, wherein characterised in that the one or more pale or transparent particulate semiconductor materials are homogeneous in structure are built up homogeneously from pale or transparent semiconductor materials or the one or more pale or transparent semiconductor materials are applied as a coating to a particulate substrate.~~
3. (Currently Amended) A method ~~Use of semiconductor materials according to Claim 1, wherein characterised in that the particulate semiconductor materials or the and particulate substrates are spherical, flake-form or needle-shaped materials or substrates.~~
4. (Currently Amended) A method ~~Use of semiconductor materials according to Claim 1, wherein characterised in that the semiconductor material is built up oxidically or sulfidically.~~
5. (Currently Amended) A method ~~Use of semiconductor materials according to Claim 1, wherein characterised in that the semiconductor material is built up on the basis of indium oxide, antimony oxide, tin oxide, zinc oxide, zinc sulfide, tin sulfide or is a mixture of the said materials.~~
6. (Currently Amended) A method ~~Use of semiconductor materials according to Claim 5, wherein characterised in that the mixture is indium-tin oxide (ITO).~~

7. (Currently Amended) A method Use of semiconductor materials
according to Claim 1, wherein ~~characterised in that~~ the substrate is selected from the group
consisting of mica flakes, SiO₂ flakes, Al₂O₃ flakes, glass flakes, aluminium flakes, BiOCl
flakes, SiO₂ spheres, glass spheres, hollow glass spheres, TiO₂ spheres, polymer spheres,
TiO₂ needles and ~~or~~ mixtures thereof.

8. (Currently Amended) A method Use of semiconductor materials
according to Claim 1, wherein ~~characterised in that~~ the semiconductor materials are doped.

9. (Currently Amended) A method Use of semiconductor materials
according to Claim 1, wherein ~~characterised in that~~ the semiconductor has an amorphous,
crystalline or microcrystalline structure.

10. (Currently Amended) A curing or drying additive composition,
comprising Formulations, ~~characterised in that they comprise~~ one or more pale or transparent
particulate semiconductor materials or particulate substrates coated with pale or transparent
semiconductor materials ~~as curing and/or drying additives.~~

11. (Currently Amended) A surface coating or printing ink composition,
comprising a curing or drying additive composition ~~Formulations~~ according to Claim 10,
~~characterised in that they are surface coatings or printing inks comprising semiconductor~~
~~materials.~~

12. (New) A curing or drying additive composition according to claim 10,
consisting essentially of one or more pale or transparent particulate semiconductor materials
or particulate substrates coated with pale or transparent semiconductor materials.

13. (New) A method according to claim 1, further comprising physically
drying in air or curing by oxidation, condensation, thermally, or by IR irradiation the surface-
coating layer or the printing ink.

14. (New) A method according to claim 1, wherein the coating layer is an

automobile paint.

15. (New) A method according to claim 1, wherein the curing or drying of a surface-coating layer is achieved.

16. (New) A method according to claim 1, wherein the curing or drying of a printing ink is achieved.

17. (New) A method for shortening the curing and/or drying time of a surface-coating layer or printing ink by about 10-60% of the drying time without the addition of one or more pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials comprising adding to the surface-coating layer or the printing ink one or more pale or transparent particulate semiconductor materials or one or more particulate substrates coated with one or more pale or transparent semiconductor materials.

18. (New) A method according to claim 17, wherein the printing ink or surface-coating layer cures or dries by IR radiation.

19. (New) A method according to claim 17, wherein the curing or drying of a surface-coating layer is achieved.

20. (New) A method according to claim 17, wherein the curing or drying of a printing ink is achieved.